

Humidity Sensor: Storage and Handling Guidelines

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ABSTRACT

Texas Instruments' family of humidity sensors, or Humidity-to-Digital Converters (HDCs), provide excellent measurement accuracy at industry's lowest power consumption levels. The low power consumption facilitates use in battery powered IoT applications such as smart thermostats, and wireless data loggers while the excellent accuracy supports applications such as white goods, smart home assistants and gas sensing. The HDC ICs come factory calibrated for ease of use and are available in small packages (WSON or DSBGA) to simplify board design.

In contrast to ordinary ICs in WSON or DSBGA packages, the exposed humidity sense layer of the HDC requires additional precautions during storage, assembly and packaging to meet datasheet performance specifications. Special handling is also required during PCB assembly. Reducing stress on the package helps to ensure the best performance. This application note describes storage and handling guidelines of humidity sensors, including the HDC1010, HDC1080, and HDC2010.

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1 Exposure to Contaminants

Humidity sensors are not standard ICs and therefore must not be exposed to particles or volatile chemicals such as solvents or other organic compounds. The opening in the package exposes the sense layer to the environment and makes it susceptible to pollutants. Typical ambient conditions do not present a significant risk for chemical exposure but manufacturing and storage environments are a known source of volatile contamination. The innovative DSBGA package of the HDC1010 and HDC2010 with the sensing element placed on the bottom part of the device (see [Figure 1](#)) makes the sensor more robust against dirt, dust, and other particulate contamination compared to the WSON solution (HDC1080).

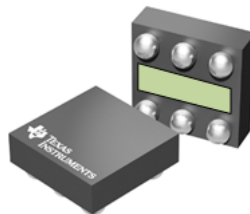


Figure 1. DSBGA Package with Sensing Element on Bottom of the Device (HDC2010)

Exposure to a range of chemicals must be avoided or minimized. Exposure of the following chemicals is known to cause drift of the humidity output readings which may be irreversible:

- Solvents such as
 - Toluene: C_7H_8
 - Acetone: $(CH_3)_2CO$
 - Ethanol: C_2H_6O

- Methanol: CH₃OH
- Isopropyl Alcohol: C₃H₈O
- Di-isopropyl Ether: C₆H₁₄O
- Ethylene Glycol: (CH₂OH)₂
- Ethyl Acetate: C₄H₈O₂
- Butyl Acetate: C₆H₁₂O₂
- Methyl Ethyl Ketone: CH₃C(O)CH₂CH₃
- Acids such as
 - Hydrochloric acid: HCl
 - Sulphuric acid: H₂SO₄
 - Nitric Acid: HNO₃
- Other Chemicals, including
 - Ketenes
 - Ammonia: NH₃
 - Hydrogen Peroxide: H₂O₂
 - Ozone: O₃
 - Formaldehyde: CH₂O

Such chemicals are an integral part of epoxies, glues, adhesives, or reaction by-products that outgas during baking and curing processes.

The sense layer must not have direct contact with cleaning agents such as PCB board wash after soldering. Applying cleaning agents to the sense layer may lead to drift of the RH output or even complete breakdown of the sensor. Avoid strong blasts from aerosol dusters and use only low pressure oil free air dusting.

If it is necessary to expose the HDC to contaminants, concentration, concentration and exposure time must be reduced as much as feasible. Good ventilation (fresh air supply) aids in lowering the concentration of volatile chemicals, particularly solvents.

2 Packaging and Storage

TI's Humidity sensors are shipped in sealed anti-static tape and reel cavities. The sensors may be stored in a humidity and temperature controlled environment after being removed from the tape and reel cavity prior to assembly. Storage temperature and humidity limitations are defined by the MSL level of the sensor. Refer to application note [MSL Ratings and Reflow Profiles](#) for details.

Do not store the humidity sensors with anti-static polyethylene bags or packing materials (pink foam) as these materials emit gases that can affect the sensor. Metallized, anti-static, sealable bags are recommended for storage. Do not use adhesives or tape inside the storage container.

3 Assembly

The HDC must be added in the last assembly step. In case the PCB passes through multiple solder cycles (as is the case for PCBs that are assembled on the top and bottom side), it is recommended to assemble the HDC in the last solder cycle. This reduces the risks of sense layer exposure. Contaminants such as those listed in [Section 1](#) must be avoided or minimized. Maximum assembly temperatures and exposure times must not be not exceeded.

NOTE: It is important that “no-clean” solder paste is used and no board wash is applied once the sensor is assembled onto the PCB.

4 Application In Extreme Environments

Some applications require usage of the HDC in harsh environments. Ensure that the exposure of the sensor to the maximum limit of temperature and humidity operating conditions meets the datasheet guidelines. Limiting exposure to volatile organic compounds at high concentration and long exposure time is critical. Usage in harsh environments must be carefully tested and qualified.

Exposure to any aqueous solutions is highly discouraged. In the event that some aqueous exposure cannot be avoided, use the following guidelines:

- Exposure to acids or bases may affect humidity output accuracy readings.
- Bases are less damaging than acid solutions. All acid solutions must be considered damaging to the sensor. Etching substances such as H_2O_2 or NH_3 at high concentrations is damaging to the sensor.
- Corrosive solutions at very low concentrations are not damaging to the sensor itself. However, care must be taken to ensure that the solder contacts are not attacked.

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